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PARMI Brings Full 3D Inspection Lineup and AI-Driven Setup Tools to APEX 2026

San Diego, CA – February 2026 – PARMI, a leader in advanced 3D inspection systems, will exhibit at the 2026 APEX EXPO, taking place March 17–19, 2026 at the Anaheim Convention Center in Anaheim, California. Visitors can find PARMI in Booth 2131, where the company will showcase its latest 3D inspection systems and AI-based inspection software for electronics manufacturing.

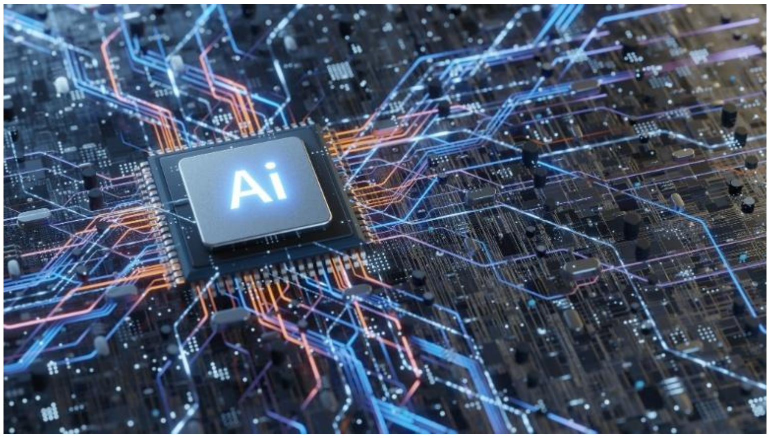
PARMI's exhibit will include key platforms across inspection and measurement needs:

- **INTELLION** – Next-generation 3D AOI platform featuring PARMI's TRCS-II sensor and a granite-based motion system for stabilized high-precision inspection.
- **PCI 100 DSI** – A precision conformal coating inspection system that uses a laser-based scanning method to inspect coating coverage, bubbles, contamination, and thickness even on tall components. It supports high-speed imaging with simultaneous UV and white LED capture for comprehensive conformal coating validation.

- **XCEED-II and XCEED DSI** – High-speed 3D AOI platforms built on PARMI's next generation dual laser scanning technology, producing real 3D images that are unaffected by board color or surface finish. These systems inspect common defects such as missing components, misalignment, tombstoning, and solder issues with consistent speed and accuracy.

- **SIGMAX** – 3D solder paste inspection (SPI) system using dual laser scanning to provide detailed measurement of height, area, volume, shape, and PCB warpage for paste and process control.

- **PRECION** – A 2D/3D AOI solution optimized for wire bond inspection down to fine diameters and detailed dimensional measurement. It uses multi-illumination and vertical Z-scan imaging to deliver precise detection of wire bonds and its related defects.



A key focus of PARMI's exhibit will be its AI-based inspection capabilities, including AI Teaching & Inspection, Auto Debugging, and AI Verification. AI Teaching & Inspection simplifies program creation by automatically generating inspection models using only a physical PCB and BOM, significantly reducing setup time and manual effort. Auto Debugging and AI Verification help manufacturers refine inspection performance, reduce false calls, and maintain consistent results across production runs.

PARMI's AI technology is built on deep learning models trained with extensive component data, enabling accurate identification of components, leads, and pads. This approach reduces variability tied to operator experience and supports faster production ramp-up while maintaining inspection reliability.

Attendees are invited to visit **Booth 2131** to see live demonstrations of PARMI's inspection systems and learn how its combination of advanced 3D hardware and AI-driven software supports tighter process control, improved yields, and efficient production in demanding electronics manufacturing environments.

For more information about PARMI and its inspection solutions, visit **www.parmi.com**.

About PARMI

PARMI is a manufacturer specializing in 3D inspection equipment used to improve print quality and yield in SMT production lines. Throughout its 26 year history, the company has specialized in developing in-house expertise in laser measurement and software support. PARMI is a global leader in Electronics product inspection in 3D. For more information, visit www.parmi.com.

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